3.3V CMOS Static RAM 1 Meg (64K x 16-Bit)

Features

- 64K x 16 advanced high-speed CMOS Static RAM
- Equal access and cycle times
 Commercial: 10/12/15/20ns
 Industrial: 10/12/15/20ns
- One Chip Select plus one Output Enable pin
 Bidirectional data inputs and outputs directly
- LVTTL-compatible
- Low power consumption via chip deselect
 Upper and Lower Byte Enable Pins
- Upper and Lower Byte Enable Pins
- Single 3.3V power supply
- Available in 44-pin Plastic SOJ, 44-pin TSOP, and 48-Ball Plastic FBGA packages

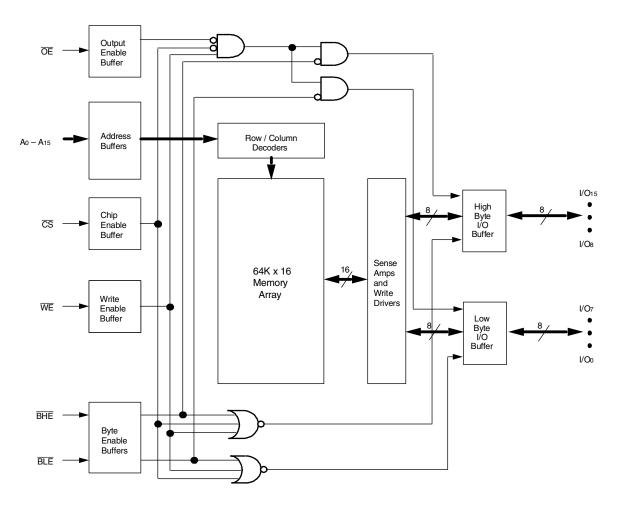
Functional Block Diagram

Description

The IDT71V016 is a 1,048,576-bit high-speed Static RAM organized as 64K x 16. It is fabricated using high-perfomance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71V016 has an output enable pin which operates as fast as 5ns, with address access times as fast as 10ns. All bidirectional inputs and outputs of the IDT71V016 are LVTTL compatible and operation is from a single 3.3V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

The IDT71V016 is packaged in a JEDEC standard 44-pin Plastic SOJ, a 44-pin TSOP Type II, and a 48-ball plastic 7 x 7 mm FBGA.

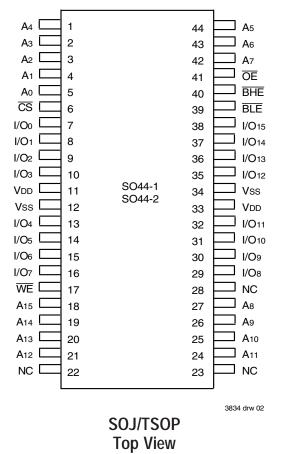


3834 drw 01

AUGUST 2013

IDT71V016SA, 3.3V CMOS Static RAM 1 Meg (64K x 16-Bit)

Pin Configurations



	1	2	3	4	5	6
A	BLE	Œ	Ao	A1	A2	NC
В	I/O8	BHE	A3	A4	NS N	I/Oo
С	I/O9	I/O10	A 5	A6	I/O1	I/O2
D	Vss	I/O11	NC	A7	I/O3	Vdd
Ε	Vdd	I/O12	NC	NC	I/O4	Vss
F	I/O14	I/O13	A14	A 15	I/O5	I/O6
G	I/O15	NC	A12	A13	WE	I/O7
Η	NC	A8	A9	A 10	A11	NC
						3834 tbl 02a

FBGA (BF48-1) Top View



Truth Table⁽¹⁾

CS	ŌĒ	WE	BLE	BHE	I/O0-I/O7	I/O 8- I/O 15	Function
Н	Х	Х	Х	Х	High-Z	High-Z	Deselected – Standby
L	L	Н	L	Н	DATAOUT	High-Z	Low Byte Read
L	L	Н	Н	L	High-Z	DATAOUT	High Byte Read
L	L	Н	L	L	DATAOUT	DATAOUT	Word Read
L	Х	L	L	L	DATAIN	DATAIN	Word Write
L	Х	L	L	Н	DATAIN	High-Z	Low Byte Write
L	Х	L	Н	L	High-Z	DATAIN	High Byte Write
L	Н	Н	Х	Х	High-Z	High-Z	Outputs Disabled
L	Х	Х	Н	Н	High-Z	High-Z	Outputs Disabled

NOTE:

1. $H = V_{IH}, L = V_{IL}, X = Don't care.$

3834 tbl 02

Commercial and Industrial Temperature Ranges

Absolute Maximum Ratings⁽¹⁾

Symbol	Rating	Value	Unit
Vdd	Supply Voltage Relative to Vss	-0.5 to +4.6	V
Vin, Vout	Terminal Voltage Relative to Vss	-0.5 to VDD+0.5	V
Tbias	Temperature Under Bias	-55 to +125	٥C
Tstg	Storage Temperature	-55 to +125	٥C
Рт	Power Dissipation	1.25	W
Ιουτ	DC Output Current	50	mA
NOTE.			3834 tbl 03

NOTE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Capacitance

$(TA = +25^{\circ}C, f = 1.0MHz, SOJ package)$

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit	
CIN	Input Capacitance	VIN = 3dV	6	pF	
Cı/o	I/O Capacitance	Vout = 3dV	7	pF	
NOTE: 3834					

NOTE:

1. This parameter is guaranteed by device characterization, but not production tested.

DC Electrical Characteristics

(VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

Recommended Operating Temperature and Supply Voltage

Grade	Temperature	Vss	Vdd
Commercial	0°C to +70°C	0V	See Below
Industrial	-40°C to +85°C	0V	See Below

3834 tbl 04

3834 tbl 05

Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vdd ⁽¹⁾	Supply Voltage	3.15	3.3	3.6	۷
VDD ⁽²⁾	Supply Voltage	3.0	3.3	3.6	۷
Vss	Ground	0	0	0	۷
Viн	Input High Voltage	2.0		VDD+0.3(3)	۷
VIL	Input Low Voltage	-0.3 ⁽⁴⁾		0.8	۷

NOTES:

1. For 71V016SA10 only.

2. For all speed grades except 71V016SA10.

3. VIH (max.) = VDD+2V for pulse width less than 5ns, once per cycle.

4. VIL (min.) = -2V for pulse width less than 5ns, once per cycle.

			IDT71V016SA		
Symbol	Parameter	Test Condition	Min.	Max.	Unit
ILI	Input Leakage Current	VDD = Max., VIN = VSS to VDD		5	μA
Ilo	Output Leakage Current	$V_{DD} = Max., \overline{CS} = V_{IH}, V_{OUT} = V_{SS} to V_{DD}$		5	μA
Vol	Output Low Voltage	IOL = 8mA, VDD = Min.		0.4	V
Vон	Output High Voltage	Ioh = $-4mA$, VDD = Min.	2.4		V

3834 tbl 07

DC Electrical Characteristics^(1,2)

(VDD = Min. to Max., VLC = 0.2V, VHC = VDD - 0.2V)

			71V016SA10		71V016SA12		71V016SA15		71V016SA20		
Symbol	Parameter		Com'l	Ind'l	Com'l	Ind'l	Com'l	Ind'l	Com'l	Ind'l	Unit
Icc	Dynamic Operating Current	Мах.	160	170	150	160	130	130	120	120	mA
	$\overline{\text{CS}} \le \text{VLC}$, Outputs Open, VDD = Max., f = fmax ⁽³⁾	Тур.(4)	65	1	60		55		50	-	
ISB	Dynamic Standby Power Supply Current $\overline{\text{CS}} \ge \text{VHc}$, Outputs Open, VDD = Max., f = fMax ⁽³⁾		45	50	40	45	35	35	30	30	mA
I SB1	Full Standby Power Supply Current (static) $\overline{CS} \ge$ VHC, Outputs Open, VDD = Max., f = 0 ⁽³⁾		10	10	10	10	10	10	10	10	mA

NOTES:

1. All values are maximum guaranteed values.

2. All inputs switch between 0.2V (Low) and VDD - 0.2V (High).

3. fMAX = 1/tRC (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing .

Typical values are based on characterization data for H step only measured at 3.3V, 25°C and with equal read and write cycles. 4.

3

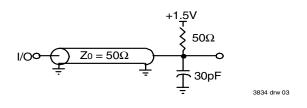
3834 tbl 08

AC Test Conditions

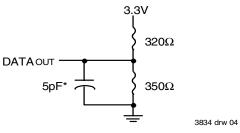
Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	1.5ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figure 1, 2 and 3

3834 tbl 09

AC Test Loads







*Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

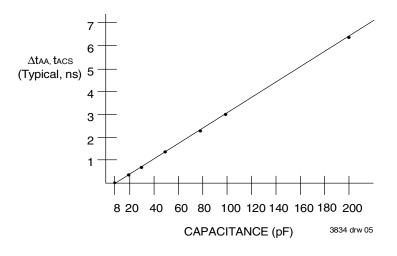


Figure 3. Output Capacitive Derating

AC Electrical Characteristics (VDD = Min. to Max., Commercial and Industrial Temperature Ranges)

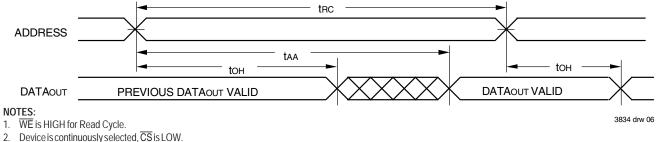
		71V016SA10		71V016SA12		71V016SA15		71V016SA20		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
READ CYCL	E		•			•				•
trc	Read Cycle Time	10		12		15		20		ns
taa	Address Access Time		10		12		15		20	ns
tacs	Chip Select Access Time		10		12		15		20	ns
tcLz ⁽¹⁾	Chip Select Low to Output in Low-Z	4	—	4		5		5		ns
tcHz ⁽¹⁾	Chip Select High to Output in High-Z		5		6		6		8	ns
toe	Output Enable Low to Output Valid		5		6		7		8	ns
tolz ⁽¹⁾	Output Enable Low to Output in Low-Z	0		0		0		0		ns
tонz ⁽¹⁾	Output Enable High to Output in High-Z		5		6		6		8	ns
toн	Output Hold from Address Change	4	_	4	_	4	_	4	_	ns
t BE	Byte Enable Low to Output Valid	_	5	_	6	_	7		8	ns
tblz ⁽¹⁾	Byte Enable Low to Output in Low-Z	0		0		0		0		ns
tbHz ⁽¹⁾	Byte Enable High to Output in High-Z		5		6		6		8	ns
WRITE CYC	LE					•				
twc	Write Cycle Time	10		12		15		20		ns
taw	Address Valid to End of Write	7		8		10		12		ns
tcw	Chip Select Low to End of Write	7		8		10		12		ns
tBW	Byte Enable Low to End of Write	7		8		10		12		ns
tas	Address Set-up Time	0		0		0		0		ns
twr	Address Hold from End of Write	0		0		0		0		ns
twp	Write Pulse Width	7		8		10	_	12		ns
tow	Data Valid to End of Write	5		6		7		9		ns
tdн	Data Hold Time	0		0		0		0		ns
tow ⁽¹⁾	Write Enable High to Output in Low-Z	3	_	3		3		3		ns
twHz ⁽¹⁾	Write Enable Low to Output in High-Z		5		6		6		8	ns

NOTE:

1. This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested.

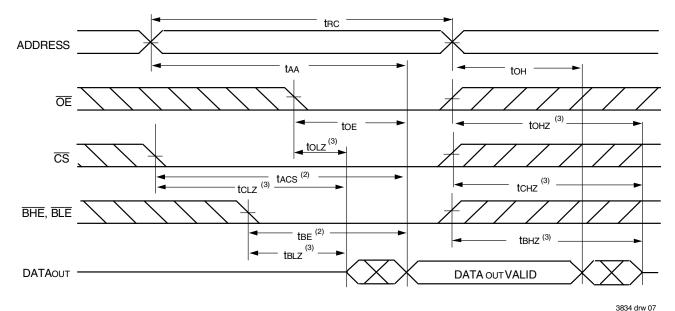
3834 tbl 10

Timing Waveform of Read Cycle No. 1^(1,2,3)



3. OE, BHE, and BLE are LOW.

Timing Waveform of Read Cycle No. 2⁽¹⁾



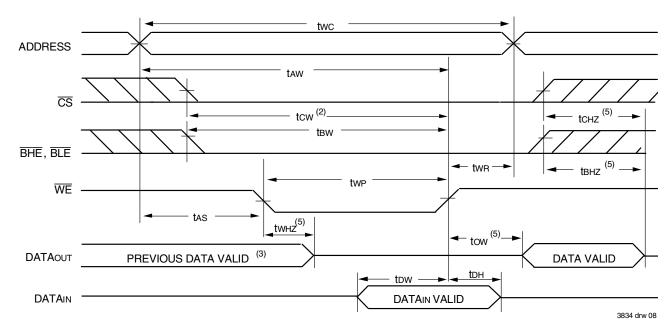
NOTES:

1. WE is HIGH for Read Cycle.

2. Address must be valid prior to or coincident with the later of CS, BHE, or BLE transition LOW; otherwise taa is the limiting parameter.

3. Transition is measured ±200mV from steady state.

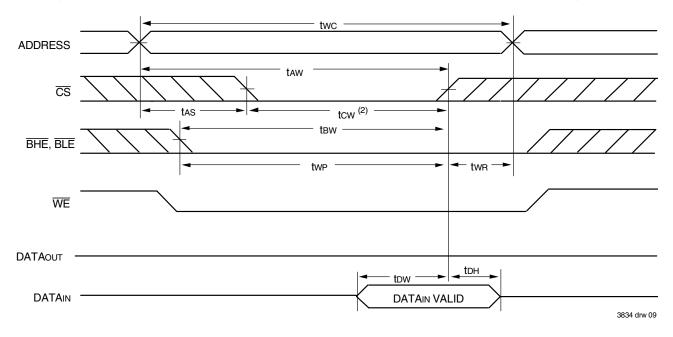
Timing Waveform of Write Cycle No. 1 (WE Controlled Timing)^(1,2,4)



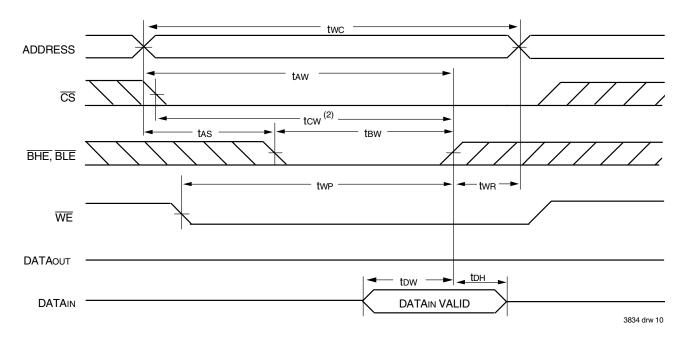
NOTES:

- 1. A write occurs during the overlap of a LOW CS, LOW BHE or BLE, and a LOW WE.
- OE is continuously HIGH. If during a WE controlled write cycle OE is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
 During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the ČS LOW or BHE and BLE LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.

Timing Waveform of Write Cycle No. 2 (CS Controlled Timing)^(1,4)

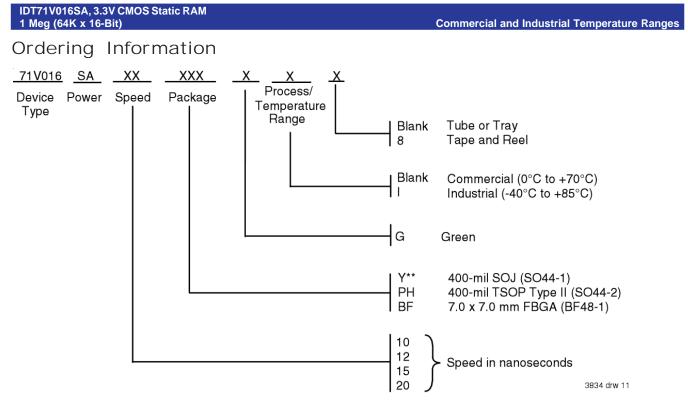


Timing Waveform of Write Cycle No. 3 (BHE, BLE Controlled Timing)^(1,4)



NOTES:

- 1. A write occurs during the overlap of a LOW \overline{CS} , LOW \overline{BHE} or \overline{BLE} , and a LOW \overline{WE} .
- 2. OE is continuously HIGH. If during a WE controlled write cycle OE is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the \overline{CS} LOW or \overline{BHE} and \overline{BLE} LOW transition occurs simultaneously with or after the \overline{WE} LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ± 200 mV from steady state.



** This package not available in 10ns Industrial temperature range.

Datasheet Document History

01/07/00	Pg. 1, 3, 5, 8 Pg. 2 Pg. 6 Pg. 7 Pg. 9	Updated to new format Added Industrial Temperature range offerings Numbered I/Os and address pins on FBGA Top View Revised footnotes on Write Cycle No. 1 diagram Revised footnotes on Write Cycle No. 2 and No. 3 diagrams Added Datasheet Document History
08/30/00	Pg. 3	Tighten Icc and IsB.
	Pg. 5	Tighten tclz, tcнz, toнz, tвнz and twнz
08/22/01	Pg. 8	Removed footnote "available in 15ns and 20ns only"
06/20/02	Pg. 8	Added tape and reel field to ordering information
01/30/04	Pg. 8	Added "Restricted hazardous substance device" to ordering information.
09/27/06	Pg. 8	Corrected ordering information, changed position of I and G.
02/14/07	Pg.8	Added H step generation to data sheet ordering information.
06/26/07	Pg.3	Changed typical parameters for ICC, DC electrical characteristics table.
10/13/08	Pg.8	Removed "IDT" from orderable part number
10/11/11	Pg.1,8	Updated datasheet with removal of Obsolete HSA part number.
08/13/13	Pg.1,3,5,8	Added 10ns for Industrial Temperature range offerings.



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 71V016SA12PHG8
 71V016SA12YGI8
 71V016SA20BFI8
 71V016SA20BFG8
 71V016SA20PHG1

 71V016SA20BFGI
 71V016SA20PHG
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 71V016SA20PHG8
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